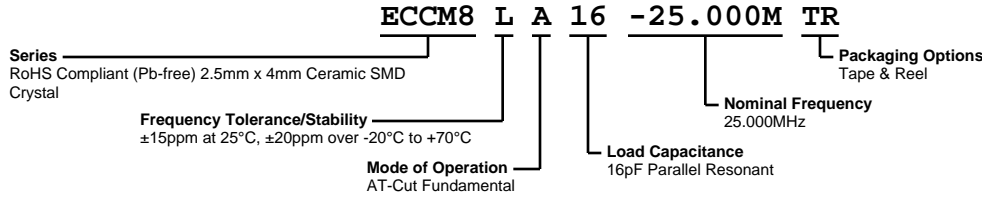


# ECCM8LA16-25.000M TR



**ECLIPTEK**  
CORPORATION



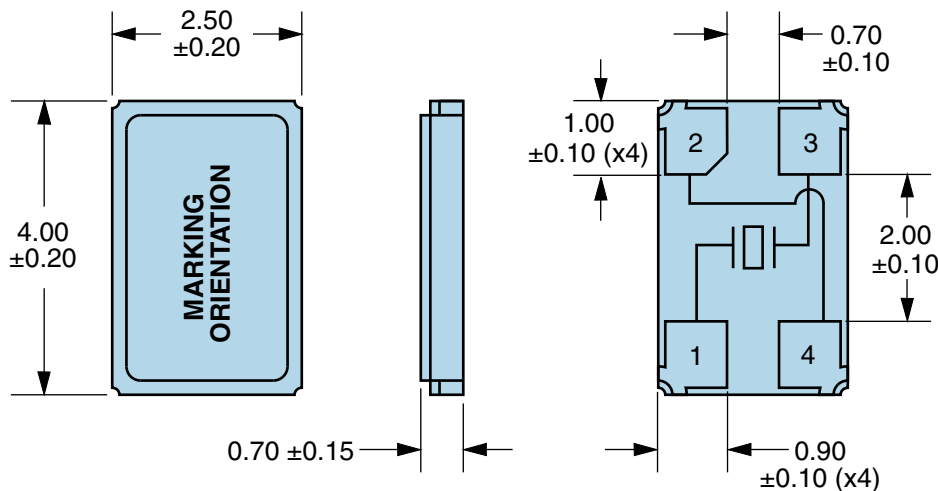
## ELECTRICAL SPECIFICATIONS

<b>Nominal Frequency</b>	25.000MHz
<b>Frequency Tolerance/Stability</b>	±15ppm at 25°C, ±20ppm over -20°C to +70°C
<b>Aging at 25°C</b>	±3ppm/Year Maximum
<b>Load Capacitance</b>	16pF Parallel Resonant
<b>Shunt Capacitance (C0)</b>	5pF Maximum
<b>Equivalent Series Resistance</b>	60 Ohms Maximum
<b>Mode of Operation</b>	AT-Cut Fundamental
<b>Drive Level</b>	100µWatts Maximum, 10µWatts Correlation
<b>Crystal Cut</b>	AT-Cut
<b>Spurious Response</b>	>3dB from Fo to Fo+5000ppm
<b>Drive Level Dependency (DLD2)</b>	20% of Maximum ESR Limit (from 1µWatt to 100µWatt)
<b>Insulation Resistance</b>	500 Megaohms Minimum at 100Vdc

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

<b>ESD Susceptibility</b>	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
<b>Fine Leak Test</b>	MIL-STD-883, Method 1014, Condition A
<b>Flammability</b>	UL94-V0
<b>Gross Leak Test</b>	MIL-STD-883, Method 1014, Condition C
<b>Mechanical Shock</b>	MIL-STD-883, Method 2002, Condition B
<b>Moisture Resistance</b>	MIL-STD-883, Method 1004
<b>Moisture Sensitivity</b>	J-STD-020, MSL 1
<b>Resistance to Soldering Heat</b>	MIL-STD-202, Method 210, Condition K
<b>Resistance to Solvents</b>	MIL-STD-202, Method 215
<b>Solderability</b>	MIL-STD-883, Method 2003
<b>Temperature Cycling</b>	MIL-STD-883, Method 1010, Condition B
<b>Vibration</b>	MIL-STD-883, Method 2007, Condition A

## MECHANICAL DIMENSIONS (all dimensions in millimeters)



PIN	CONNECTION
1	Crystal
2	Cover/Ground
3	Crystal
4	Cover/Ground

LINE	MARKING
1	<b>E25.0</b> E=Ecliptek
2	<b>XXXXX</b> XXXXX=Ecliptek Manufacturing Identifier